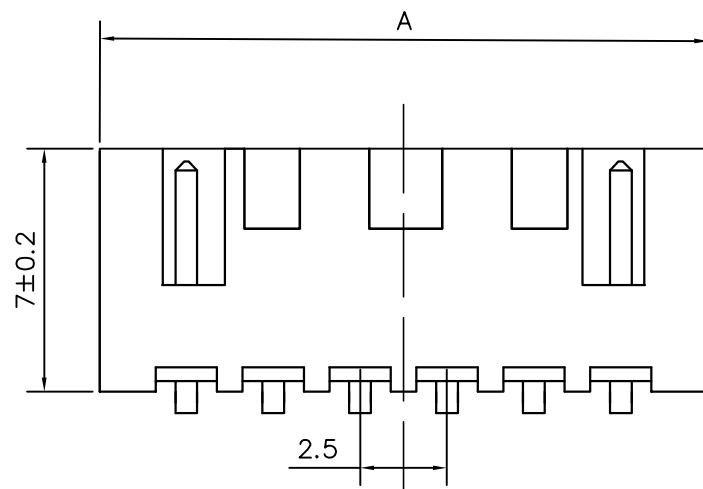
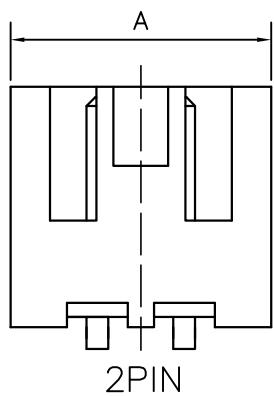


| 标记 MARK | ECN编号/变更内容 ECN NO/DEFINITION | 修改 REVISE | 日期 DATE | 核准 APPROVE |
|------------|---------------------------------|--------------|------------|---------------|
| | | | | |
| | | | | |

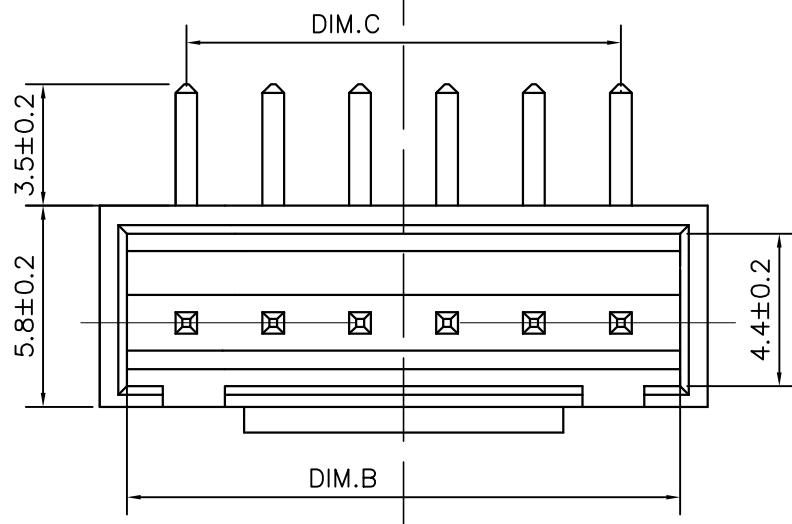
A



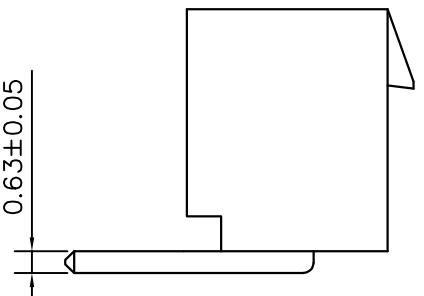
B



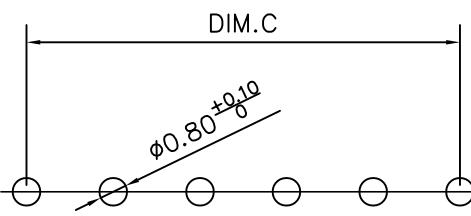
C



D



E



PCB LAYOUT

技术要求:

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25°C~85°C
 额定电压: 250V AC/DC
 额定电流: 3A
 接触电阻: ≤0.01Ω
 绝缘电阻: ≥1000MΩ
 耐压: 1000V AC/minute

| | | | | |
|-------------|--|---------------|--------------|---------------|
| 2 | 插针 | 铜 | 镀锡 | |
| 1 | 基座 | PA66 | 米色 | |
| 序号 | 品名 | 材质 | 电镀/颜色 | 备注 |
| | | 品名 TITLE | 针座 | |
| | | 料号 PART NO | HC-XHB-8AW-M | |
| | GENERAL TOLERANCES (UNLESS SPECIFIED) | 比列 SCALE | 1:1 | |
| X.X ±0.35 | X: ±3.00° | 单位 UNIT | MM | 制图 DRAW |
| X.XX ±0.25 | X.X: ±2.00° | 张数 PART NO | 1 OF 1 | 审核 CHECKED |
| X.XXX ±0.15 | X.XX: ±1.00° | 版本 REV | A | 批准 APPROVE |
| | | | | 夏操云 |
| | | | | 赵亮亮 |



深圳市虹成电子有限公司

